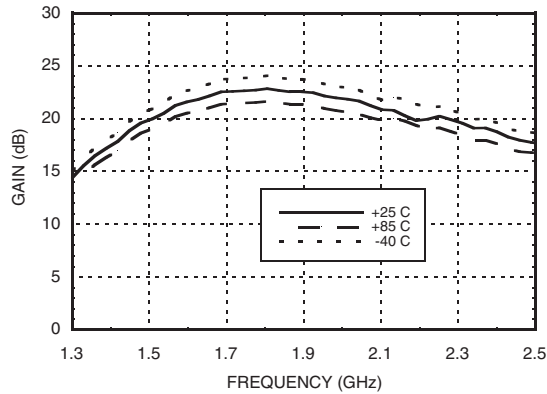
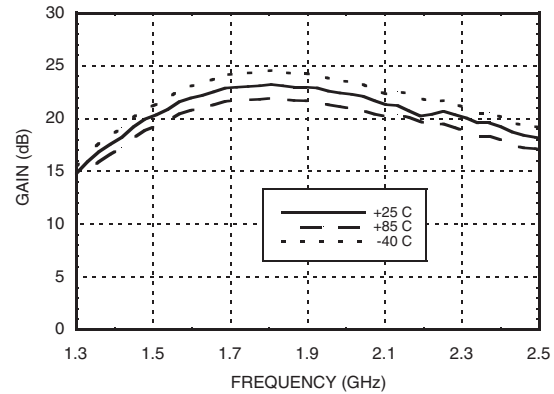
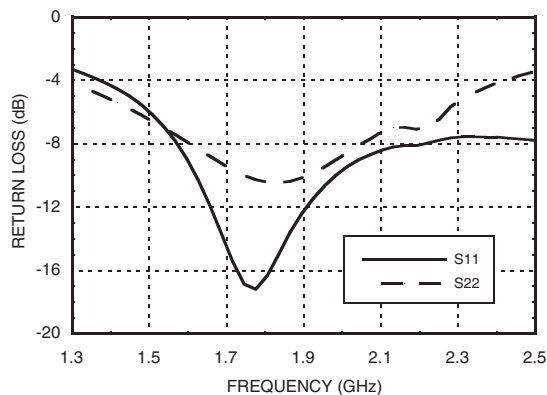
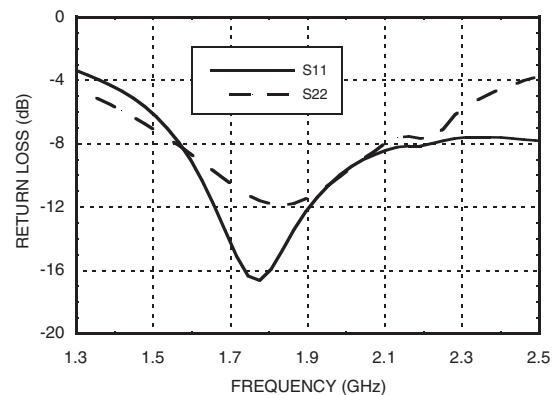
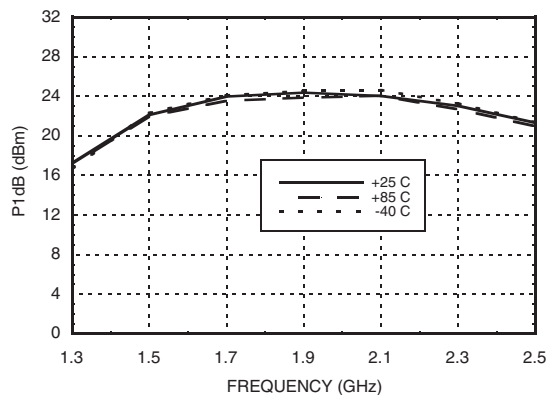
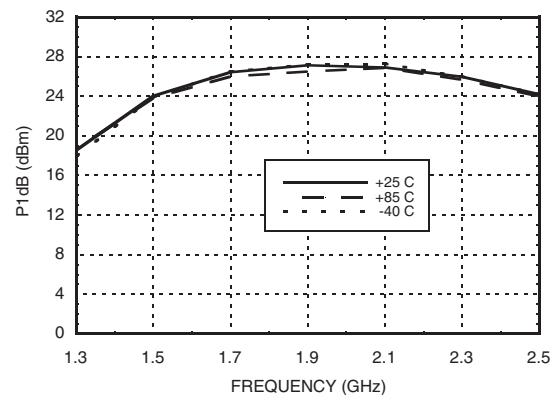
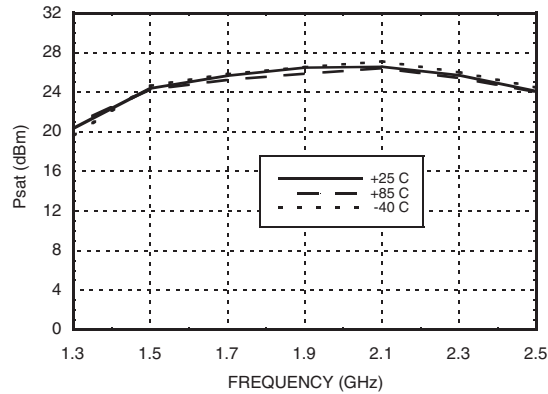
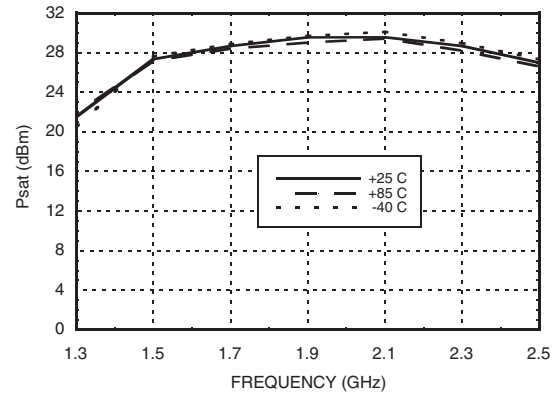
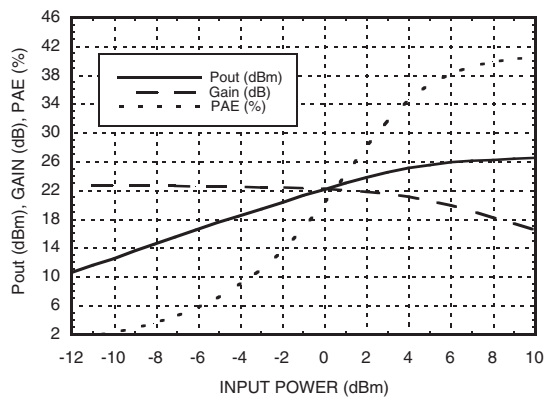
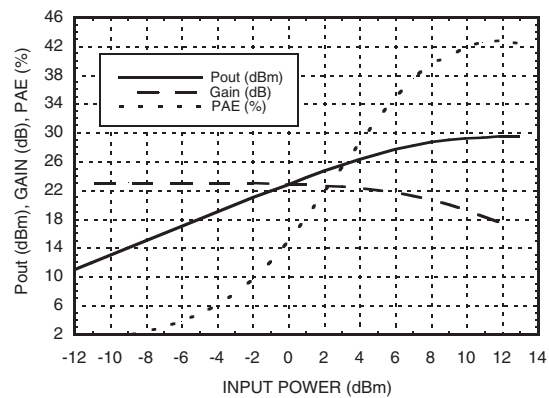
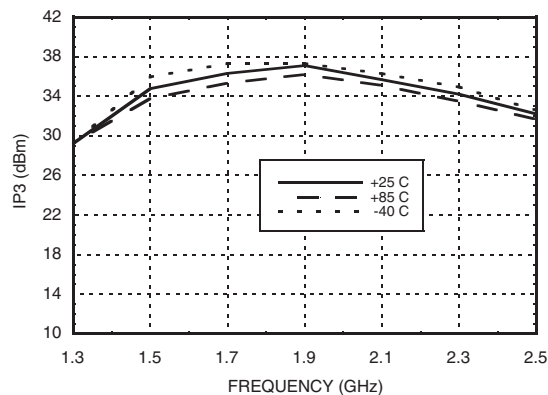
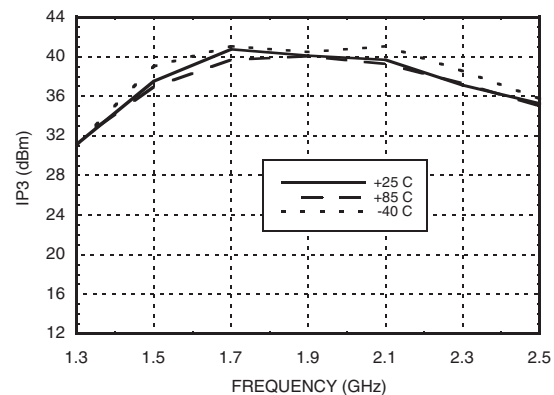


Gain vs. Temperature, $V_s = 3.6V$

Gain vs. Temperature, $V_s = 5V$

Return Loss, $V_s = 3.6V$

Return Loss, $V_s = 5V$

P1dB vs. Temperature, $V_s = 3.6V$

P1dB vs. Temperature, $V_s = 5V$


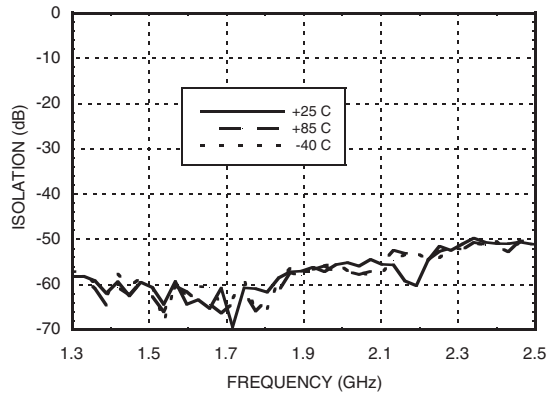
Psat vs. Temperature, Vs= 3.6V

Psat vs. Temperature, Vs= 5V

Power Compression@ 1.9 GHz, Vs= 3.6V

Power Compression@ 1.9 GHz, Vs= 5V

Output IP3 vs. Temperature, Vs= 3.6V

Output IP3 vs. Temperature, Vs= 5V




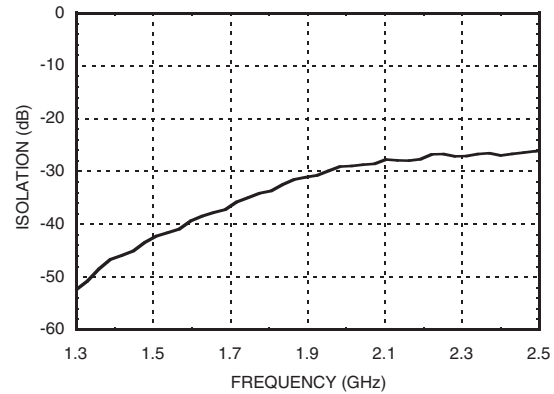
HMC413QS16G / 413QS16GE

GaAs InGaP HBT MMIC POWER AMPLIFIER, 1.6 - 2.2 GHz

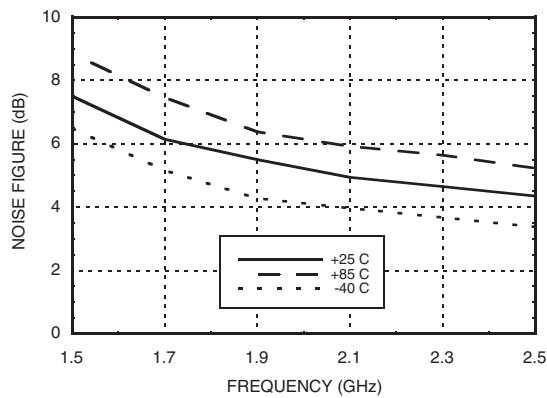
Reverse Isolation vs. Temperature, $V_s = 3.6V$



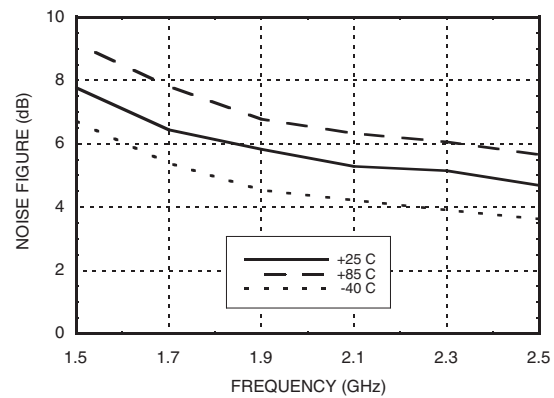
Power Down Isolation, $V_s = 3.6V$



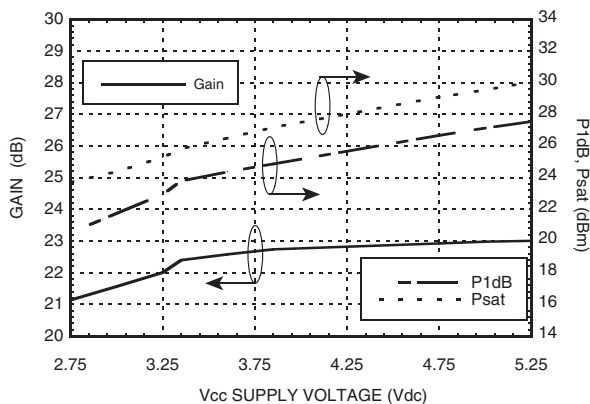
Noise Figure vs. Temperature, $V_s = 3.6V$



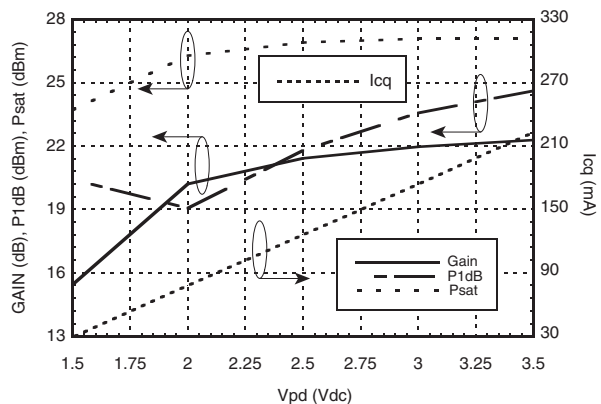
Noise Figure vs. Temperature, $V_s = 5V$



Gain & Power vs. Supply Voltage @ 1.9 GHz



Gain, Power & Quiescent Supply Current vs. V_{pd} @ 1.9 GHz, $V_{cc} = +3.6V$



Collector Bias Voltage (Vcc)	+5.5 Vdc
Control Voltage (Vpd1, Vpd2)	+4.0 Vdc
RF Input Power (RFIN)(Vs = +5Vdc, Vpd = +3.6 Vdc)	+15 dBm
Junction Temperature	150 °C
Continuous P _{diss} (T = 85 °C) (derate 24 mW/°C above 85 °C)	1.56 W
Thermal Resistance (junction to ground paddle)	42 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C


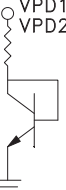
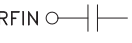
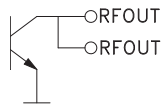
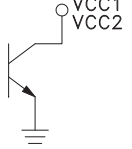
The drawing shows the mechanical specifications for the HMCNNN package. The top view is a square package with 16 pins on the top edge (pins 16 to 9) and 8 pins on the bottom edge (pins 1 to 8). The package is labeled "HMCNNN" and "XXXX" (where XXXX represents the lot number). Dimensions include a total width of .197 inches (5.00 mm), a pin pitch of .012 inches (0.30 mm), and a total height of .158 inches (4.00 mm). The side view shows a maximum height of .069 inches (1.75 mm) and a base thickness of .005 inches (0.13 mm).

1. LEADFRAME MATERIAL: COPPER ALLOY
2. DIMENSIONS ARE IN INCHES [MILLIMETERS].
3. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.
4. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
5. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.

Part Number	Package Body Material	Lead Finish	MSL Rating	Package Marking ^[3]
HMC413QS16G	Low Stress Injection Molded Plastic	Sn/Pb Solder	MSL1 ^[1]	HMC413 XXXX
HMC413QS16GE	RoHS-compliant Low Stress Injection Molded Plastic	100% matte Sn	MSL1 ^[2]	<u>HMC413</u> XXXX

For price, delivery, and to place orders: Analog Devices, Inc.,
One Technology Way, P.O. Box 9106, Norwood, MA 02062-9106
Phone: 781-329-4700 • Order online at www.analog.com
Application Support: Phone: 1-800-ANALOG-D

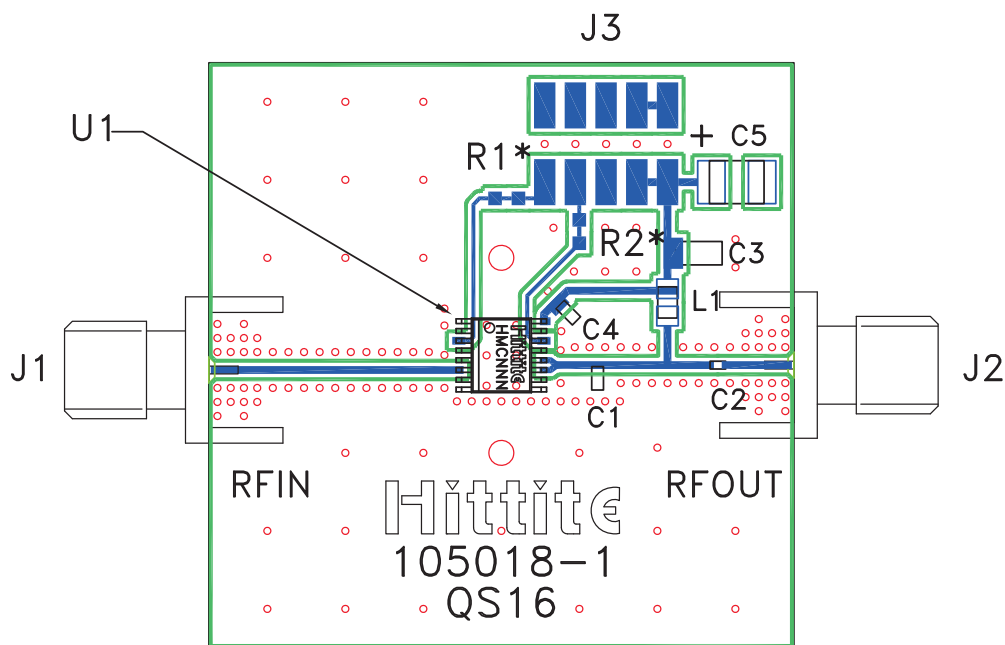
Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1, 2, 4, 5, 7, 8, 9, 10, 13, 15	GND	Ground: Backside of package has exposed metal ground slug that must be connected to ground thru a short path. Vias under the device are required.	
3, 14	Vpd1, Vpd2	Power Control Pin. For maximum power, this pin should be connected to 3.6V. For 5V operation, a dropping resistor is required. A higher voltage is not recommended. For lower idle current, this voltage can be reduced.	
6	RFIN	This pin is AC coupled and matched to 50 Ohms from 1.6 to 2.2 GHz.	
11, 12	RFOUT	RF output and bias for the output stage.	
16	Vcc	Power supply voltage for the first amplifier stage. An external bypass capacitor of 330 pF is required as shown in the application schematic.	



**GaAs InGaP HBT MMIC
POWER AMPLIFIER, 1.6 - 2.2 GHz**

Evaluation PCB



* For 5V operation on Vctl line, select R1, R2 such that 3.6V is presented on Pins 3 and 14.

List of Materials for Evaluation PCB 105000 [1]

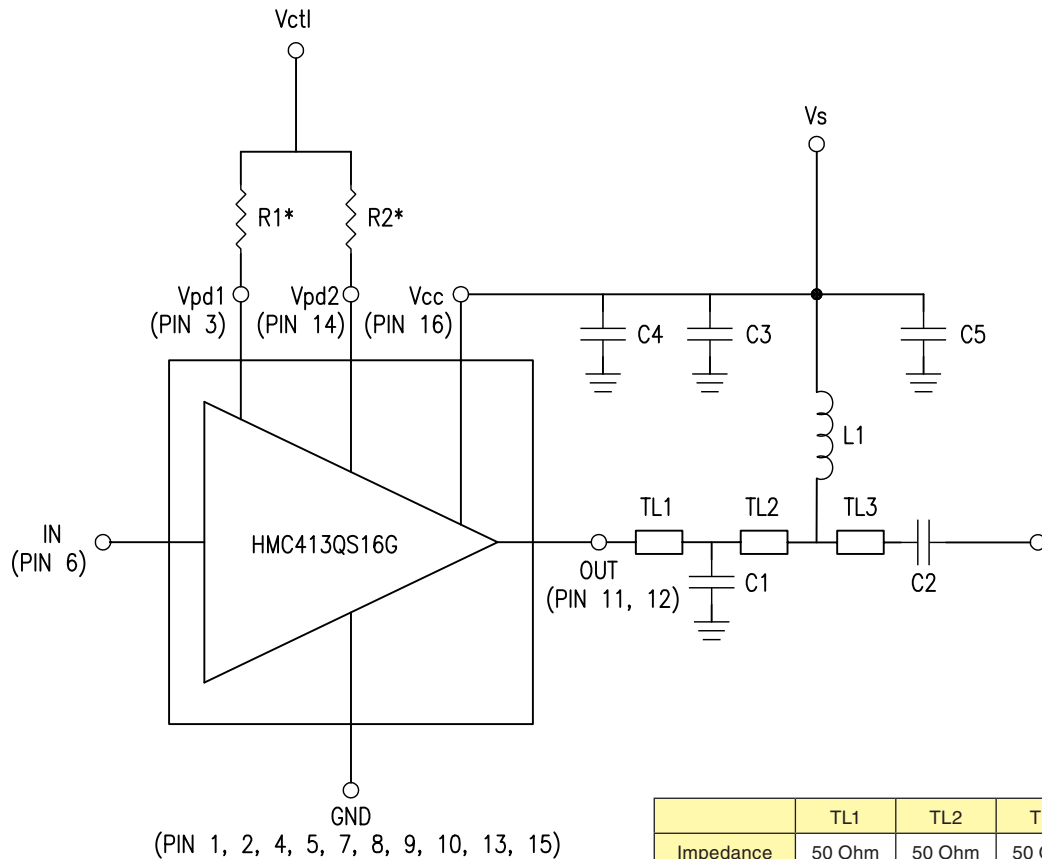
Item	Description
J1 - J2	PCB Mount SMA RF Connector
J3	2 mm DC Header
C1	2.2 pF Capacitor, 0603 Pkg.
C2	10 pF Capacitor, 0402 Pkg.
C3 - C4	330 pF Capacitor, 0603 Pkg.
C5	2.2 μ F Capacitor, Tantalum
L1	16 nH Inductor 0603 Pkg.
U1	HMC413QS16G / HMC413QS16GE Amplifier
PCB [2]	105018 Eval Board

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

Application Circuit



* For 5V operation on Vctl line, select R1, R2 such that 3.6V is presented on Pins 3 and 14.